

Abstract

In a pressure bonding mechanism having a configuration in which a first pressure bonding tool 21A and a second pressure bonding tool 21B mounted on elevating rods 18A and 18B are elevated by a common numerically-controllable tool elevating mechanism 16 through an engagement member 17 so that pressure is applied to the pressure bonding tools by a first air cylinder 19A and a second air cylinder 19B respectively, the height positions of the pressure bonding surfaces of the first pressure bonding tool 21A and the second pressure bonding tool 21B in the state where the elevating rods 18A and 18B are in engagement with the engagement member 17 so as to regulate the lower limit positions of the elevating rods 18A and 18B are made different from each other. Thus, the pressure bonding tools can be brought into contact with substrates in turn respectively. It is therefore unnecessary to provide high-precision and high-cost elevating means individually for the pressure bonding tools.